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mounting the spring in the getter well that elastic forces in the spring retain it in a selected position; and  
sealing the getter well to the metallization [metallization] layer.

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1 (amended). An electrode and getter structure for a gas discharge device that includes a frame having a cavity therein that contains a gain medium and an electrode bore extending from a surface of the frame to the cavity, comprising:

a metallization layer formed on the surface of the frame, the metallization layer including an electrode that is adjacent the electrode bore;  
a getter well sealed to the metallization layer around the electrode bore; and  
a getter mounted in the getter well spaced apart from the frame.

3 (amended). The electrode and getter structure of claim 1 wherein the metallization layer includes an electrical contact arranged so that an electrical signal may be applied to the electrode.

4 (amended). The electrode and getter structure of claim 1 wherein the getter well comprises a hollow glass cylinder having a closed end and an open end mounted to the metallization layer.

5 (amended) The electrode and getter structure of claim 4 further comprising a spring retained in the getter well being attached to the getter and aligned with the electrode bore, the spring being arranged to support the getter.

6 (amended). An electrode and getter structure for a gas discharge device that includes a frame having a cavity therein that contains a gain medium and an electrode bore extending from a surface of the frame to the cavity, comprising:

a metallization layer formed on the surface of the frame, the metallization layer including:

a ring that extends around the electrode bore and is spaced apart therefrom;

an electrode formed in the metallization layer to extend inward in the ring to a location adjacent the electrode bore; and

an electrical contact in the metallization layer and arranged to extend away from the ring;

a getter well sealed to the metallization layer;

a spring mounted in the getter well such that elastic forces in the spring retain it in a selected position; and

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a getter mounted in the getter well spaced apart from the frame and aligned with the electrode bore.

7 (amended). A method for forming an electrode and getter structure for a gas discharge device that includes a frame having a cavity therein that contains a gain medium and an electrode bore extending from a surface of the frame to the cavity, comprising the steps of:

forming a metallization layer on the surface of the frame, the metallization layer being formed to include an electrode that is adjacent the electrode bore; sealing a getter well to the metallization layer around the electrode bore; and mounting a getter in the getter well spaced apart from the frame.

8 (amended). The method of claim 7 including the steps of forming the metallization layer to extend around the electrode bore; and securing the getter well to the metallization layer.

9 (amended). The method of claim 8 including the step of forming the metallization layer to include an electrical contact arranged so that an electrical signal may be applied to the electrode.

12 (amended). A method for forming a gas discharge device that includes a frame having a cavity therein that contains a gain medium and an electrode bore extending from a surface of the frame to the cavity, comprising:

forming a metallization layer as a ring that extends around the electrode bore and is spaced apart therefrom on the surface of the frame;

forming an electrode in the metallization layer that extends inward in the ring to a location adjacent the electrode bore; and

forming an electrical contact in the metallization layer extending away from the ring;

providing a getter well;

mounting a getter to a spring;

mounting the spring in the getter well that elastic forces in the spring retain it in a selected position; and

sealing the getter well to the metallization layer.